

AMENDMENT TO THE SPECIFICATION

Please amend the specification paragraphs set forth below to read as follows:

Paragraph beginning at page 7, line 10:

FIGURE 1 is a cross-section schematic diagram of a two-layer carrier structure comprising a carrier liner 10 and a cross-linkable adhesive layer 20. Carrier structures of the present invention may also include cross-linkable adhesive layers 20 comprising a combination of permanent tacky controlled peel strength adhesive and thermal-UV releasing adhesive within a single layer 20. Thus, differential peel strength is produced after thermal-UV exposure. The adhesive layer 20 first releases the chips or other objects carried and then releases the carrier base 10, enabling the replacement of adhesive layer 20 for reuse of typical carrier base 10. Such a combination adhesive preferably releases both chips 60 and liner 10 without leaving a residue, and also preferably has greater adhesion to liner 10 than to the chip or other object 60 carried so that the chip is released more easily than is the liner 10, i.e. it has a different release profile from the chip than from the liner 10.

Paragraph beginning at page 12, line 18:

The second layer 30 of the adhesive laminate should be coated with a strong adhesive, e.g. about 100-5000 gm/inch, that will not be dramatically affected by thermal-UV or other radiation exposure. This second, non-curable adhesive layer 30 should be easily removable from the carrier base 10, so that the carrier base 10 can be reused after application of a new adhesive laminate. Thus, second layer 30 has a different release profile than does first layer 20.

Paragraph beginning at page 20, line 1:

All of these high-surface-energy polymers may be used for baking out moisture, e.g., at about 150°C. If extended exposure to higher temperature of about 200-350°C for

a few minutes must be used, the more useful polymers will be those of polyvinylidene fluoride or its copolymer. Some of block co-polymers such as Kraton G series made by Shell Chemical Company or similar thermoplastic elastomer resin with high temperature stable backbone may be used. Preferably the adhesive has a higher and more permanent adhesion to the carrier base film or liner 10, 10a, 10b than to the items to be carried, i.e. has a different release profile to carrier base film or liner 10 than to the items, and that the adhesive layer 20 be of sufficient thickness (typically about 1-5 mil) to hold parts with slightly different flatness tolerances.